



US00D857674S

(12) **United States Design Patent** (10) **Patent No.:** **US D857,674 S**
Man (45) **Date of Patent:** **** Aug. 27, 2019**

(54) **RFID TAG INLAY**
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(**) Term: **15 Years**
(21) Appl. No.: **29/633,090**
(22) Filed: **Jan. 12, 2018**

D713,827 S * 9/2014 Forster D14/230
D719,936 S * 12/2014 Forster D14/230
D740,261 S * 10/2015 Man D14/230
D758,357 S * 6/2016 Man D14/230
D761,235 S * 7/2016 Man D14/230
D773,442 S * 12/2016 Man D14/230
D780,722 S * 3/2017 Forster D14/230
D786,222 S * 5/2017 Forster D14/230
D788,744 S * 6/2017 Forster D14/230
D794,001 S * 8/2017 Ota D14/230
D803,195 S * 11/2017 Man D14/230
D809,488 S * 2/2018 Forster D14/230
D822,649 S * 7/2018 He D14/230
D828,340 S * 9/2018 Forster D14/230
D836,616 S * 12/2018 Escaro D14/230
2012/0092027 A1 * 4/2012 Forster G05D 22/02
324/658

(30) **Foreign Application Priority Data**

Jul. 28, 2017 (HK) 1701482

(51) **LOC (12) Cl.** **14-03**

(52) **U.S. Cl.**
USPC **D14/230**

(58) **Field of Classification Search**
USPC D14/138, 230-238, 299, 358; D12/42, D12/43
CPC H01Q 7/00; H01Q 13/10; H01Q 9/285;
H01Q 19/30; H01Q 19/12; H01Q 1/38;
H01Q 1/36; H01Q 2/0027; H01Q 1/48;
H01Q 9/045; H01Q 1/243; H04B 1/0475;
H04B 1/034; H05K 11/00

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D704,171 S * 5/2014 Forster D14/230
D710,338 S * 8/2014 Forster D14/230

* cited by examiner

Primary Examiner — John Windmuller

(57) **CLAIM**

The ornamental design for an RFID tag inlay, as shown and described.

DESCRIPTION

The sole FIGURE is a front elevational view of an RFID tag inlay showing my new design. The solid black areas constitute the entirety of the claimed design. All elements of the claimed design are flat and coplanar.

1 Claim, 1 Drawing Sheet



